

Die Bonding Operator

Aliases: Die Bonding Operator, Die Attach Operator

Industry/Sector(s): Electronics and HW

JOB DESCRIPTION ¹

The tasks a Wire Bonding Operator is expected to perform include:

- Attaching the silicon die or micro-chip on a lead frame or PCB, respectively
- Operating the automated pick-and-place machine to solder or paste the silicon die or chip on a lead frame or PCB

WORK ENVIRONMENT

- It needs one to be on their toes
- Work from home is not available
- Part-time and contractual jobs may not be available
- Local traveling is not a part of this job role
- Need not handle a team

Working hours

- Working is 9 hours everyday for 6 days a week
- Shift system may be applicable

Is the job suitable for a candidate with special needs?

Maybe

EDUCATIONAL QUALIFICATIONS AND TRAINING ¹

- Minimum – Preferably 12th standard passed
- Certified training for Die Bonding Operator (programme aligned to ELE/Q1701 released by Electronics Sector Skills Development Council)

KEY COMPETENCIES ¹

- Proficient in operating the pick-and-place machine
- Proficient in carrying out preventive maintenance of machine as per manufacturer's schedule
- Skilled at maintaining ESD, dust-free and 5S standards as per company's policy
- Knowledge of maintaining a safe and healthy working environment at the workplace
- Proficient at handling hazardous material
- Knowledge of electrostatic discharge (ESD) measures for electronic component safety

DESIRABLE COMPETENCIES ¹

- Knowledge of disposal of hazardous chemicals, tools and materials by following prescribed environmental norms
- Safety procedures while operating hazardous tools and equipment

AVAILABLE SKILL TRAINING AND LEARNING INSTITUTES

- Technical institutes across India
- ITIs across India

AVAILABLE SKILL TRAINING SCHEMES/SCHOLARSHIPS

<http://nscsindia.org/AboutUs.aspx>
<http://www.ejobshub.in/2013/12/iocl-scholarship-2014-2015-download.html>

SAMPLE OF TRAINING AND LEARNING COURSES

<http://www.sdct.goa.gov.in/Prospectus1314.pdf>

CAREER PROGRESSION PATH

Wire Bonding Operator → Supervisor → Manager

Transfer option

•India: Yes

•Abroad: Yes

*(*This field to open the relevant job title when clicked)*

EXPECTED EARNINGS

•For freshers – ₹ 7,000 to ₹ 9,000 per month

•For candidates with experience - ₹ 10,000 to ₹ 15,000 per month

(These figures are indicative and subject to change)

REQUIRED WORK EXPERIENCE ¹

Not applicable

PROBABLE EMPLOYERS

•Manufacturing companies

•Packaging solutions companies

PEOPLE'S CORNER

Coming Soon

KEYWORDS

Wire Bonding, Die Attach. Die bonding

OCCUPATIONAL CODES AND STANDARDS

Standard	Code	Description
NCO 2015	8212.1702	Die Bonding Operator
ISCO 2008	8212	Electrical and Electronic Equipment Assemblers
NIC 2008	26104	Manufacture of bare printed circuit boards, loading of components onto printed circuit boards; manufacture of interface cards (e.g. sound, video, controllers, network, modems)
QP Reference	ELE/Q1701	Die Bonding Operator
NSQF	4	NA

REFERENCES

1	1 Qualification Pack – Die Bonding Operator
2	http://www.prnewswire.com/news-releases/india-electrical-capacitor-market-to-grow-at-36-until-2019-says-techsci-research-272272931.html
3	3 “Human Resource and Skill Requirements in the IT and ITeS Industry Sector (2022)” released by NSDC
4	www.censusindia.gov.in
5	http://www.nsdcindia.org/sites/default/files/files/Electronics-IT-hardware.pdf